

阅读申明

- 1.本站收集的数据手册和产品资料都来自互联网，版权归原作者所有。如读者和版权方有任何异议请及时告之，我们将妥善解决。
- 2.本站提供的中文数据手册是英文数据手册的中文翻译，其目的是协助用户阅读，该译文无法自动跟随原稿更新，同时也可能存在翻译上的不当。建议读者以英文原稿为参考以便获得更精准的信息。
- 3.本站提供的产品资料，来自厂商的技术支持或者使用者的心得体会等，其内容可能存在描述上的差异，建议读者做出适当判断。
- 4.如需与我们联系，请发邮件到marketing@iczoom.com，主题请标有“数据手册”字样。

Read Statement

1. The datasheets and other product information on the site are all from network reference or other public materials, and the copyright belongs to the original author and original published source. If readers and copyright owners have any objections, please contact us and we will deal with it in a timely manner.
2. The Chinese datasheets provided on the website is a Chinese translation of the English datasheets. Its purpose is for reader's learning exchange only and do not involve commercial purposes. The translation cannot be automatically updated with the original manuscript, and there may also be improper translations. Readers are advised to use the English manuscript as a reference for more accurate information.
3. All product information provided on the website refer to solutions from manufacturers' technical support or users the contents may have differences in description, and readers are advised to take the original article as the standard.
4. If you have any questions, please contact us at marketing@iczoom.com and mark the subject with "Datasheets" .



Customer Information Notification

201311006I

Issue Date: 02-Jan-2014
Effective Date: 03-Feb-2014

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to [view this notification online](#)



Management Summary

NXP will introduce new reel design for lighter packing using less material.

Change Category

- | | | | |
|--|---|---|---|
| <input type="checkbox"/> Wafer Fab process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input checked="" type="checkbox"/> Packing/Shipping/Labeling |

Introducing lighter reels for tape & reel packing at APG and APM

Information Notification

As announced through GN 2013100002 NXP will introduce a new reel design using less materials.

Through this CIN NXP communicates the introduction of three reels at assembly sites APG and APM. These reels have been tested and fulfill our packing requirements and are in compliance with EIA-481D and IEC60286-3.

Conversion for the products in this phase will start per February 2014, to be finalized in 2014 (please see remark).

Stock of reels with 'old' design will be used up before delivery of products in light weight reels will start. In the conversion period current and light weight reels might be mixed, but considering the fact that they are fully compatible, this will not hamper processing at customers.

For detailed information we invite you to view this notification online where a file is attached which indicates what the

change looks like and what has been tested to release this.

Why do we issue this Information Notification

This change enables environmental improvement by reducing waste materials.

Identification of Affected Products

Products from APG and APM can be identified by the country of origin information on the packing label or by the vendor code on the product marking (if space permits).

Impact

No impact to the product's functionality anticipated. The major dimensions will not change, reels are fully compatible with the reels currently used.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Remarks

As soon as we have a more detailed (monthly / weekly) planning we will put this in the CIN, see details as indicated on page 1.

Attached to this CIN:

A one page powerpoint presentation showing reel examples and a table showing tests that will be done to release the reels.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA Customer Support
e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

A global semiconductor company with operations in more than 25 countries, NXP posted unaudited revenue of \$4.36 billion in 2012.

You have received this email because you are a designated contact or subscribed to NXP's Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[View Notification](#)

[Subscription](#)

[Support](#)

[NXP](#) | [Privacy Policy](#) | [Terms of Use](#)

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.